

[54] HEAT RELEASING PLATE FOR MOUNTING SEMICONDUCTOR COMPONENTS

[75] Inventor: Yoshihiko Asanuma, Tochigi, Japan

[73] Assignee: Showa Aluminum Kabushiki Kaisha, Osaka, Japan

[\*\*] Term: 14 Years

[21] Appl. No.: 154,971

[22] Filed: May 30, 1980

[30] Foreign Application Priority Data

Mar. 31, 1980 [TW] Taiwan ..... 6930607

[51] Int. Cl. .... D13-03

[52] U.S. Cl. .... D13/23

[58] Field of Search ..... D13/23; 165/80 R, 80 A, 165/80 B, 80 D; 357/81; 174/16 HS

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Primary Examiner—Susan J. Lucas  
Attorney, Agent, or Firm—Armstrong, Nikaido, Marmelstein & Kubovcik

[57] CLAIM

The ornamental design for heat releasing plate for mounting semiconductor components, as shown and described.

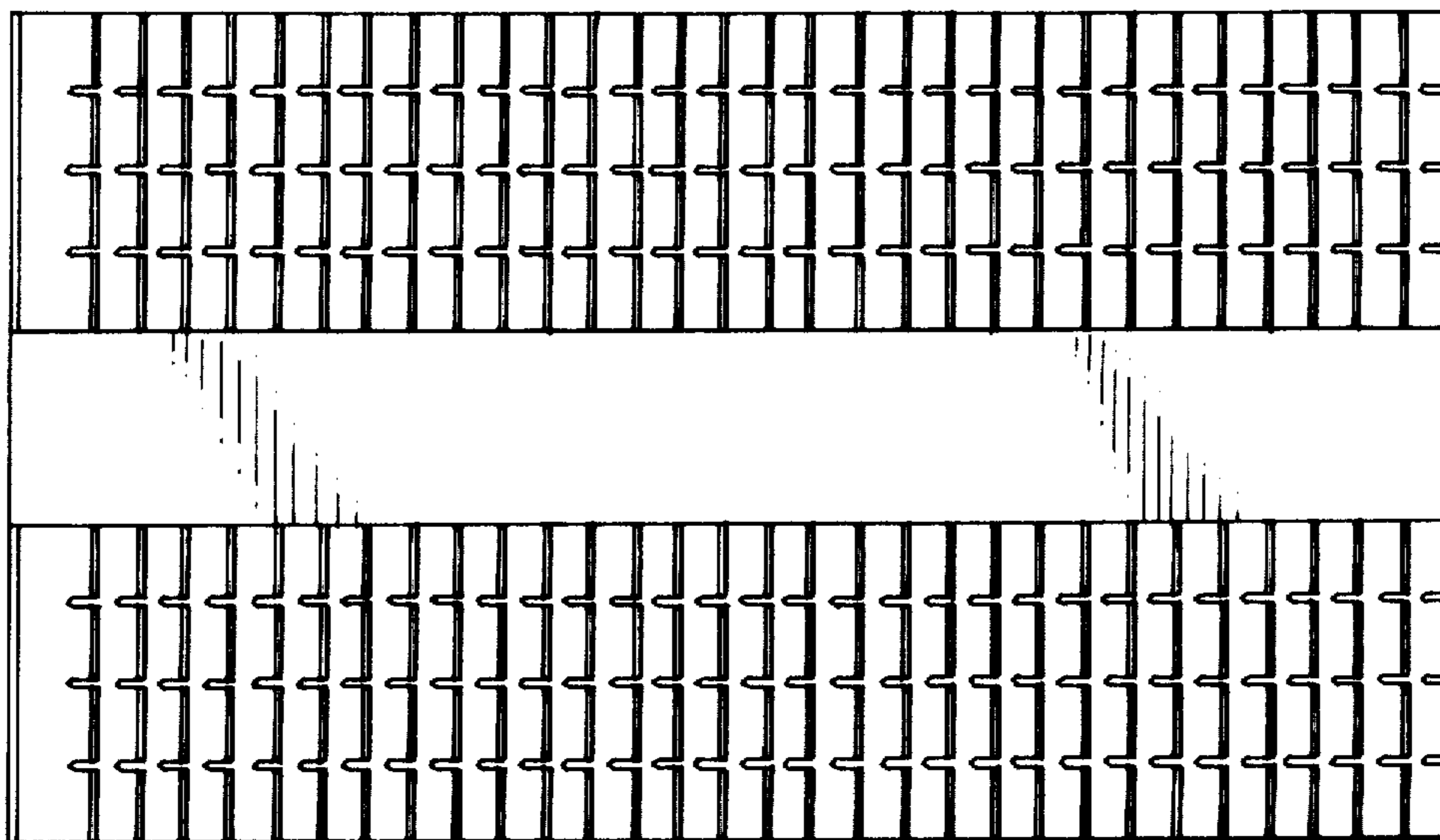
DESCRIPTION

FIG. 1 is a front view of the heat releasing plate for mounting semiconductor components showing the new design;

FIG. 2 is a plan view thereof;

FIG. 3 is a right side view thereof; and

FIG. 4 is a sectional view taken on line 4-4 of FIG. 1.



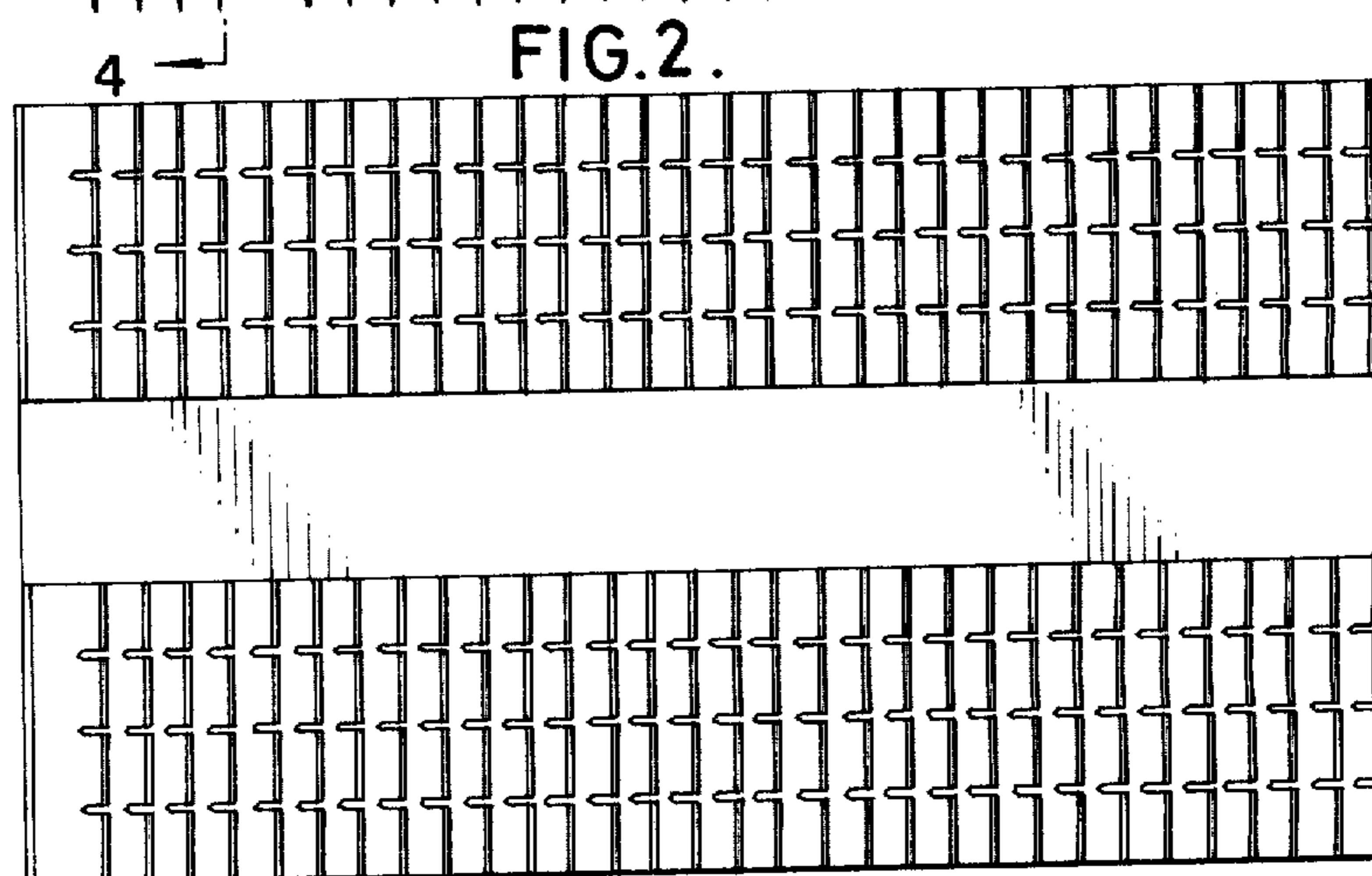
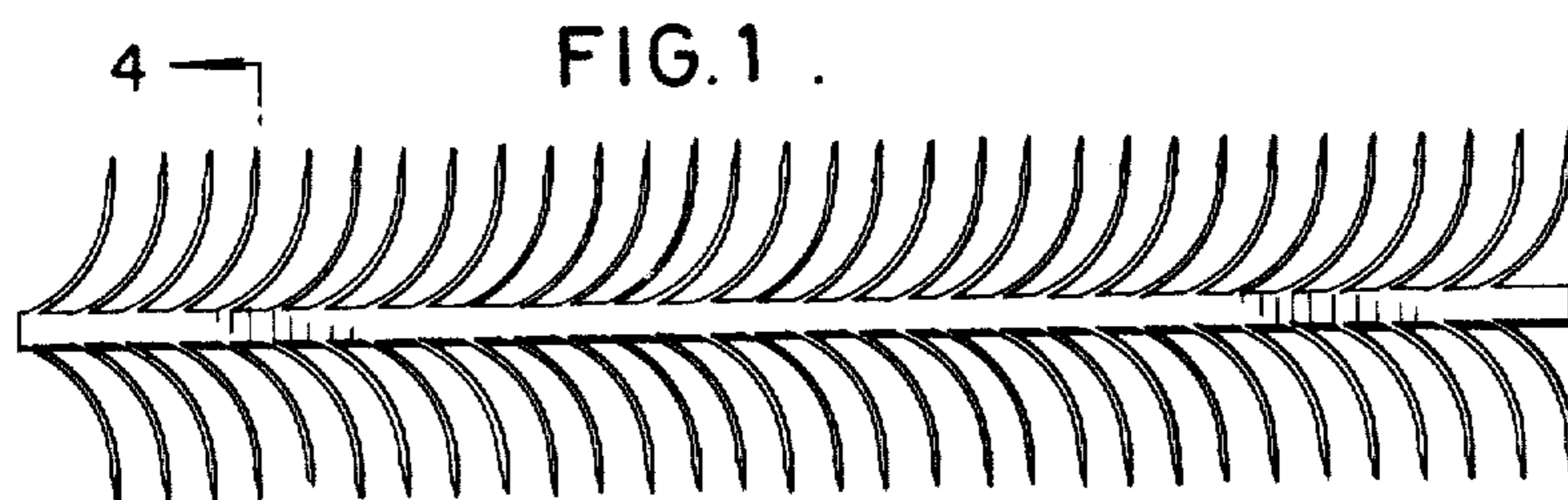


FIG. 3 .

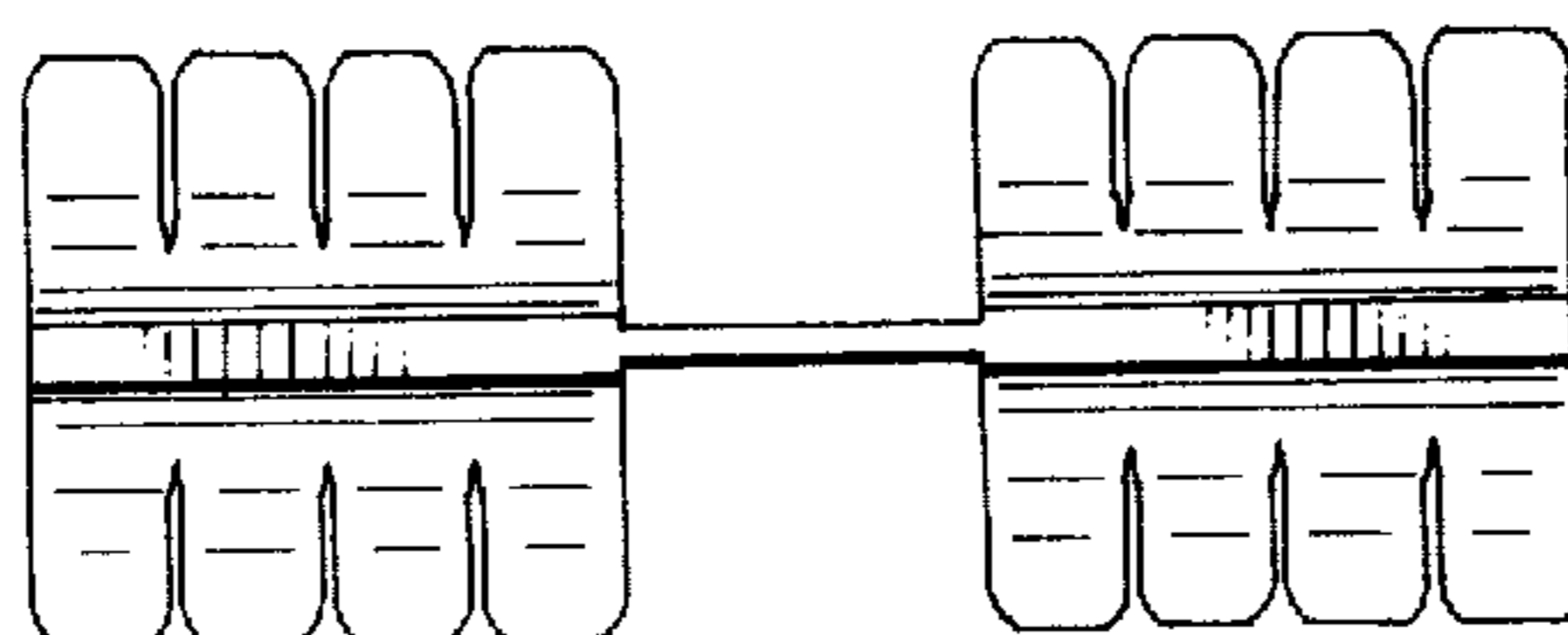


FIG. 4 .

